



**Press Release**

## **Unisem Advanced Technologies Develops Stress Buffer to Protect Semiconductor Device Features**

**Kuala Lumpur, Malaysia – January 25, 2010** – Unisem Advanced Technologies (UAT), a leading provider of wafer bumping technologies, today announced that it has developed a methodology for creating a stress buffer to protect delicate features of semiconductor devices.

This customizable stress buffer structure includes a polymer layer formed by one or multiple coatings, and a metal stack overlaying the polymer. The structure serves as a bunker to protect sensitive devices within its coverage from external stress. Its use may extend beyond stress mitigation, including shielding of sensitive devices from lights, moisture and electromagnetic interferences.

UAT's manufacturing capabilities for patterning fine dimension features are perfectly suited for creating unique patterns of stress buffer structures for each device. UAT has a patent pending on this unique process.

"Conventional semiconductor packages offer little or no additional protection to sensitive device features" said S.C. Lau, general manager of UAT. "We are excited about the unique solution we have created to help our customers protect these features in a way that is highly effective and cost efficient", continued Lau.

### **About UAT**

UAT is a 3-party joint venture between Unisem, Advanpack Solutions and Flip Chip International. Located at the same premise as Unisem Ipoh, customers receive seamless integration of a wide variety of services under one roof covering wafer bumping, wafer backgrinding, wafer probe, dicing, final test and flip-chip assembly.

UAT offers gold bumps, copper pillar bumps and solder bumps (through ball drop, plating and solder paste printing). Additionally, UAT provides repassivation and bond pad redistribution services.

**About Unisem**

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about Unisem, please visit [www.unisemgroup.com](http://www.unisemgroup.com).

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